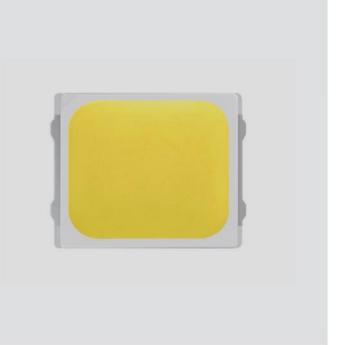
Middle Power LED Series 2835 0.5W Ra80

LM281B+



Designed for better Im/\$ (Ambient, Linear)







Features & Benefits

- 0.5W Class mid power LED
- Standard form factor for design flexibility (2.8 × 3.5 mm)



Table of Contents

1.	Characteristics	 3
2.	Product Code Information	 6
3.	Typical Characteristics Graphs	 16
4.	Outline Drawing & Dimension	 19
5.	Reliability Test Items & Conditions	 20
6.	Soldering Conditions	 21
7.	Tape & Reel	 22
8.	Label Structure	 25
9.	Packing Structure	 26
0.	Precautions in Handling & Use	 30



1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +85	°C	-
Storage Temperature	T_{stg}	-40 ~ +85	°C	-
LED Junction Temperature	Tj	115	°C	-
Forward Current	l _F	160	mA	-
Peak Pulsed Forward Current	I _{Fp}	300	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	2	kV	-

Note:

Proper current derating must be observed to maintain junction temperature below the maximum at all time.



b) Electro-optical Characteristics (I_F = 150 mA, T_s = 25 °C)

ltem	Unit	Rank	Bin	Min.	Тур.	Max.
			A1	2.8		2.9
		WA	A2	2.9		3.0
Forward Voltage (VF)	V	or	A3	3.0		3.1
		WK	A4	3.1		3.2
		•••	A 5	3.2		3.3
Color Rendering Index (Ra)	-	5		80	_	_
Thermal Resistance (junction to solder point)	°C/W			-	25	-
Beam Angle	o			-	120	-

Note:

Samsung maintains measurement tolerance of: forward voltage = ± 0.1 V, CRI = ± 3



b) Electro-optical Characteristics (I_F = 150 mA, T_s = 25 °C)

ltore	CRI (R _a)	Nominal CCT (K)	Die	150	OmA
Item	Min.	CCT (K)	Bin	Min.	Max.
			SA	52.5	56.5
		0700	SC	56.5	60.5
		2700	SE	60.5	64.5
			SG	64.5	68.5
			SA	54.5	58.5
		2000	SC	58.5	62.5
		3000	SE	62.5	66.5
			SG	66.5	70.5
			SA	55.5	59.5
	80	2500	SC	59.5	63.5
		3500	SE	63.5	67.5
			SG	67.5	71.5
		4000	SA	58.0	62.0
Luminous Flux (Φν)			SC	62.0	66.0
Editiiiodo Fida (4V)	00		SE	66.0	70.0
			SG	70.0	74.0
			SA	59.0	63.0
		5000	SC	63.0	67.0
		5000	SE	67.0	71.0
			SG	71.0	75.0
			SA	58.5	62.5
		5700	SC	62.5	66.5
		3700	SE	66.5	70.5
			SG	70.5	74.5
			SA	58.0	62.0
		6500	SC	62.0	66.0
		6500	SE	66.0	70.0
			SG	70.0	74.0

Note:

Samsung maintains measurement tolerance of: forward voltage = ± 0.1 V, luminous flux = ± 5 %, CRI = ± 3



2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	Р	М	w	н	1	2	2	8	F	D	5	w	Δ	R	0	S	С

Digit	PKG Information	Code			Specification		
1 2 3	Samsung Package Middle Power	SPM	Middle power				
4 5	Color	WH	White				
6	Product Version	1	1st version	1			
7 8 9	Form Factor	228	2.8 x 3.5 x	0.65 mm	ı; 2 pads		
10	Sorting Current (mA)	F	150 mA				
11	Chromaticity Coordinates	D	ANSI Star	ndard			
12	CRI	5	Min. 80				
13 14	Forward Voltage (V)	WA or WK	2.8~3.2	Bin code	A1 2.8 ~ 2.9 A2 2,9 ~ 3.0 A3 3.0 ~ 3.1 A4 3.1 ~ 3.2 A5 3.2 ~ 3.3		
			WA: 4,000	0ea per re	eel ,WK : 12,000ea per reel		
15 16	CCT (K)	W☆ V☆ U☆ T☆ R☆ Q☆ P☆	2700 3000 3500 4000 5000 5700 6500 ☆ : "0'	Bin Code:	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG R1, R2, R3, R4, R5, R6, R7, R8, R9,RA,RB,RC,RD,RE,RF,RG Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9,QA,QB,QC,QD,QE,QF,QG P1, P2, P3, P4, P5, P6, P7, P8, P9,PA,PB,PC,PD,PE,PF,PG Din) "M" (Quarter bin) or "K" (K Kitting bin)		
17 18	Luminous Flux	SA SC SE SG	SA Bin SC Code SE SG				



a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 25^{\circ}\text{C}$)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ _v , lm)
		SPMWH1228FD5WAW☆SA	SA	52.5 ~ 56.5
		SPMWH1228FD5WAW∻SC	SC	56.5 ~ 60.5
	2700	SPMWH1228FD5WAW☆SE	SE	60.5 ~ 64.5
		SPMWH1228FD5WAW∻SG	SG	64.5 ~ 68.5
		SPMWH1228FD5WAV☆SA	SA	54.5 ~ 58.5
	2000	SPMWH1228FD5WAV∻SC	SC	58.5 ~ 62.5
	3000	SPMWH1228FD5WAV☆SE	SE	62.5 ~ 66.5
		SPMWH1228FD5WAV☆SG	SG	66.5 ~ 70.5
		SPMWH1228FD5WAU☆SA	SA	55.5 ~ 59.5
	3500	SPMWH1228FD5WAU☆SC	SC	59.5 ~ 63.5
	3300	SPMWH1228FD5WAU☆SE	SE	63.5 ~ 67.5
		SPMWH1228FD5WAU☆SG	SG	67.5 ~ 71.5
		SPMWH1228FD5WAT☆SA	SA	58.0 ~ 62.0
80	4000	SPMWH1228FD5WAT☆SC	SC	62.0 ~ 66.0
00	4000	SPMWH1228FD5WAT☆SE	SE	66.0 ~ 70.0
		SPMWH1228FD5WAT☆SG	SG	70.0 ~ 74.0
		SPMWH1228FD5WAR☆SA	SA	59.0 ~ 63.0
	5000	SPMWH1228FD5WAR☆SC	SC	63.0 ~ 67.0
	3000	SPMWH1228FD5WAR☆SE	SE	67.0 ~ 71.0
		SPMWH1228FD5WAR☆SG	SG	71.0 ~ 75.0
		SPMWH1228FD5WAQ☆SA	SA	58.5 ~ 62.5
	5700	SPMWH1228FD5WAQ☆SC	SC	62.5 ~ 66.5
	3700	SPMWH1228FD5WAQ☆SE	SE	66.5 ~ 70.5
		SPMWH1228FD5WAQ∻SG	SG	70.5 ~ 74.5
		SPMWH1228FD5WAP☆SA	SA	58.0 ~ 62.0
	6500	SPMWH1228FD5WAP☆SC	SC	62.0 ~ 66.0
	0300	SPMWH1228FD5WAP☆SE	SE	66.0 ~ 70.0
		SPMWH1228FD5WAP☆SG	SG	70.0 ~ 74.0

Note:

 $"_{\not \approx}"$ can be "0" (Whole bin), "M" (Quarter bin) or "K" (K Kitting bin) of the color binning



b) Kitting rule

1) K Kitting bin Concept

- 1. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
- 2. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (A1+A1), (A2+A2), (A3+A3), (A4+A4) or (A5+A5).
- 3. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

[Kitting example]

D	E	F	G
9	А	В	С
5	6	7	8
1	2	3	4

[Binning Information]

	Bin #1	Bin #2		
	A1	A1		
	A2	A2		
VF	А3	A3		
	A4	A4		
	A5	A5		
	1, 2, 5 bin	C, F, G bin		
CIE	6, 7, A, B bin	6, 7, A, B bin		
	3, 4, 8 bin	9, D, E bin		



c) Color Bins ($I_F = 150$ mA, $T_s = 25$ °C)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins
		SPMWH1228FD5WAW0S★	W0 (Whole bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
	2700	SPMWH1228FD5WAWMS★	WM (Quarter bin)	W6, W7, WA, WB
		SPMWH1228FD5WAWKS★	WK (K Kitting bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
		SPMWH1228FD5WAV0S★	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
	3000	SPMWH1228FD5WAVMS★	VM (Quarter bin)	V6, V7, VA, VB
		SPMWH1228FD5WAVKS★	VK (K Kitting bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
		SPMWH1228FD5WAU0S★	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
	3500	SPMWH1228FD5WAUMS★	UM (Quarter bin)	U6, U7, UA, UB
		SPMWH1228FD5WAUKS★	UK (K Kitting bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
		SPMWH1228FD5WAT0S★	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
80	4000	SPMWH1228FD5WATMS★	TM (Quarter bin)	T6, T7, TA, TB
		SPMWH1228FD5WATKS★	TK (K Kitting bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
		SPMWH1228FD5WAR0S★	R0 (Whole bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9 RA,RB,RC,RD,RE,RF,RG
	5000	SPMWH1228FD5WARMS★	RM (Quarter bin)	R6, R7, RA, RB
		SPMWH1228FD5WARKS★	RK (K Kitting bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9 RA,RB,RC,RD,RE,RF,RG
		SPMWH1228FD5WAQ0S★	Q0 (Whole bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9 QA,QB,QC,QD,QE,QF,QG
	5700	SPMWH1228FD5WAQMS★	QM (Quarter bin)	Q6, Q7, QA, QB
		SPMWH1228FD5WAQKS★	QK (K Kitting bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9 QA,QB,QC,QD,QE,QF,QG
		SPMWH1228FD5WAP0S★	P0 (Whole bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9 PA,PB,PC,PD,PE,PF,PG
	6500	SPMWH1228FD5WAPMS★	PM (Quarter bin)	P6, P7, PA, PB
		SPMWH1228FD5WAPKS★	PK (K Kitting bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9 PA,PB,PC,PD,PE,PF,PG

Note:

" \bigstar " can be "SA", "SC", "SE" or "SG" of luminous flux bin

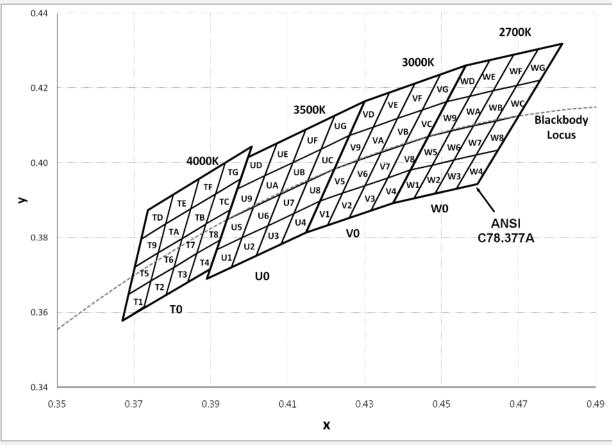


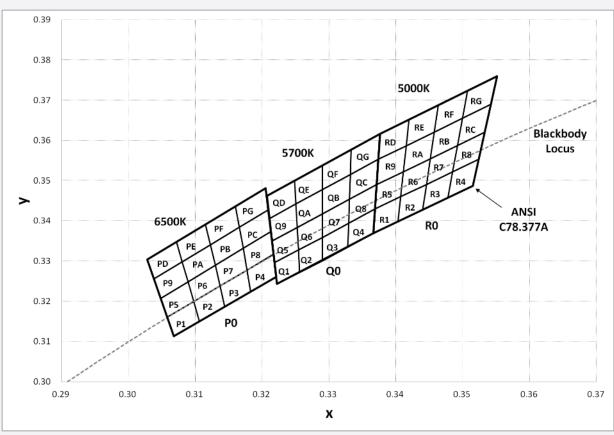
d) Voltage Bins (I_F = 150 mA, T_s = 25 °C)

CRI (R₃) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
				A1	2.8 ~ 2.9
				A2	2.9 ~ 3.0
-	-	-	WA or	АЗ	3.0 ~ 3.1
			WK ·	A4	3.1 ~ 3.2
				A 5	3.2 ~ 3.3



e) Chromaticity Region & Coordinates (I_F = 150 mA, T_s = 25 °C)







Region	CIEx	CIE y	Region	CIE x	CIE y
	:	W rank	(2700 K)		
	0.4373	0.3893		0.4465	0.4071
10/4	0.4418	0.3981		0.4513	0.4164
W1	0.4475	0.3994	W9	0.4573	0.4178
	0.4428	0.3906		0.4523	0.4085
	0.4428	0.3906		0.4523	0.4085
14/0	0.4475	0.3994	10/0	0.4573	0.4178
W2	0.4532	0.4008	· WA	0.4634	0.4193
	0.4483	0.3919		0.4582	0.4099
	0.4483	0.3919		0.4582	0.4099
14/0	0.4532	0.4008	NAD.	0.4634	0.4193
W3	0.4589	0.4021	WB	0.4695	0.4207
	0.4538	0.3931	**	0.4641	0.4112
	0.4538	0.3931		0.4641	0.4112
	0.4589	0.4021	WC	0.4695	0.4207
W4	0.4646	0.4034		0.4756	0.4221
	0.4593	0.3944	•	0.4700	0.4126
	0.4418	0.3981		0.4513	0.4164
)A/5	0.4465	0.4071	IMP	0.4562	0.4260
W5	0.4523	0.4085	WD	0.4624	0.4274
	0.4475	0.3994		0.4573	0.4178
	0.4475	0.3994		0.4573	0.4178
	0.4523	0.4085		0.4624	0.4274
W6	0.4582	0.4099	WE	0.4687	0.4289
	0.4532	0.4008	•	0.4634	0.4193
	0.4532	0.4008		0.4634	0.4193
	0.4582	0.4099		0.4687	0.4289
W7	0.4641	0.4112	WF	0.4750	0.4304
	0.4589	0.4021		0.4695	0.4207
	0.4589	0.4021		0.4695	0.4207
	0.4641	0.4112		0.4750	0.4304
W8	0.4700	0.4126	WG	0.4813	0.4319
	0.4646	0.4034		0.4756	0.4221

Region	CIEx	CIEy	Region	CIEx	CIE y
		V rank	(3000 K)		
	0.4147	0.3814		0.4221	0.3984
14	0.4183	0.3898		0.4259	0.4073
V1	0.4242	0.3919	- V9	0.4322	0.4096
	0.4203	0.3833		0.4281	0.4006
	0.4203	0.3833		0.4281	0.4006
	0.4242	0.3919		0.4322	0.4096
V2	0.4300	0.3939	VA	0.4385	0.4119
	0.4259	•	0.4342	0.4028	
	0.4259	0.3853		0.4342	0.4028
	0.4300	0.3939		0.4385	0.4119
V3	0.4359	0.3960	VB	0.4449	0.4141
	0.4316	0.3873	**	0.4403	0.4049
	0.4316	0.3873		0.4403	0.4049
	0.4359	0.3960	VC	0.4449	0.4141
V4	0.4418	0.3981		0.4513	0.4164
	0.4373	0.3893	•	0.4465	0.4071
	0.4183	0.3898		0.4259	0.4073
	0.4221	0.3984		0.4299	0.4165
V5	0.4281	0.4006	- VD	0.4364	0.4188
	0.4242	0.4006 VD 0	0.4322	0.4096	
	0.4242	0.3919		0.4322	0.4096
	0.4281	0.4006		0.4364	0.4188
V6	0.4342	0.4028	VE	0.4430	0.4212
	0.4300	0.3939		0.4385	0.4119
	0.4300	0.3939		0.4385	0.4119
\/7	0.4342	0.4028	\ /-	0.4430	0.4212
V7	0.4403	0.4049	VF	0.4496	0.4236
	0.4359	0.3960		0.4449	0.4141
	0.4359	0.3960		0.4449	0.4141
) (C	0.4403	0.4049		0.4496	0.4236
V8	0.4465	0.4071	VG	0.4562	0.4260
	0.4418	0.3981		0.4513	0.4164



Region	CIE x	CIE y	Region	CIE x	CIE y
		U rank	(3500 K)		
	0.3889	0.3690		0.3941	0.3848
114	0.3915	0.3768	110	0.3968	0.3930
U1	0.3981	0.3800	U9	0.4040	0.3966
	0.3953	0.3720	0.4	0.4010	0.3882
	0.3953	0.3720		0.4010	0.3882
110	0.3981	0.3800		0.4040	0.3966
U2	0.4048	0.3832	UA	0.4113	0.4001
	0.4017	0.3751		0.4113	0.3916
	0.4017	0.3751		0.4080	0.3916
	0.4048	0.3832		0.4113	0.4001
U3	0.4116	0.3865	UB	0.4186	0.4037
	0.4082	0.3782		0.4150	0.3950
	0.4082	0.3782		0.4150	0.3950
	0.4116	0.3865	UC	0.4186	0.4037
U4	0.4183	0.3898		0.4259	0.4073
	0.4147	0.3814		0.4221	0.3984
	0.3915	0.3768		0.3968	0.3930
	0.3941	0.3848		0.3996	0.4015
U5	0.4010	0.3882	UD	0.4071	0.4052
	0.3981	0.3800		0.4040	0.3966
	0.3981	0.3800		0.4040	0.3966
	0.4010	0.3882		0.4071	0.4052
U6	0.4080	0.3916	UE	0.4146	0.4089
	0.4048	0.3832		0.4113	0.4001
	0.4048	0.3832		0.4113	0.4001
	0.4080	0.3916		0.4146	0.4089
U7	0.4150	0.3950	UF	0.4222	0.4127
	0.4116	0.3865		0.4186	0.4037
	0.4116	0.3865		0.4186	0.4037
	0.4150	0.3950		0.4222	0.4127
U8	0.4221	0.3984	UG	0.4299	0.4165
	0.4183	0.3898		0.4259	0.4073

Region	CIEx	CIE y	Region	CIEx	CIE y
		T rank	(4000 K)		
	0.3670	0.3578		0.3702	0.3722
T-4	0.3726	0.3612	T0	0.3763	0.3760
T1	0.3744	0.3685	T9	0.3782	0.3837
	0.3686	0.3649	0.3685	0.3719	0.3797
	0.3726	0.3612		0.3763	0.3760
T2	0.3783	0.3646	TA	0.3825	0.3798
	0.3804	0.3721	IA	0.3847	0.3877
	0.3744	744 0.3685 0.378 783 0.3646 0.382	0.3782	0.3837	
	0.3783	0.3646		0.3825	0.3798
Τ0	0.3840	0.3681	TD	0.3887	0.3836
Т3	0.3863	0.3758	TB	0.3912	0.3917
	0.3804	0.3721		0.3847	0.3877
	0.3840	0.3681	TC	0.3887	0.3837
Τ4	0.3898	0.3716		0.3950	0.3875
T4	0.3924	0.3794		0.3978	0.3958
	0.3863	0.3758		0.3912	0.3917
	0.3686	0.3649		0.3719	0.3797
TE	0.3744	0.3685	TD	0.3782	0.3837
T5	0.3763	0.3760	TD	0.3802	0.3916
	0.3702	0.3722		0.3736	0.3874
	0.3744	0.3685		0.3782	0.3837
Te	0.3804	0.3721	T F	0.3847	0.3877
T6	0.3825	0.3798	TE	0.3869	0.3958
	0.3763	0.3760		0.3802	0.3916
	0.3804	0.3721		0.3847	0.3877
T7	0.3863	0.3758	T F	0.3912	0.3917
T7	0.3887	0.3836	TF	0.3937	0.4001
	0.3825	0.3798		0.3869	0.3958
	0.3863	0.3758		0.3912	0.3917
то	0.3924	0.3794	TO.	0.3978	0.3958
T8	0.3950	0.3875	TG	0.4006	0.4044
	0.3887	0.3836		0.3937	0.4001



Region	CIEx	CIE y	Region	CIE x	CIE y
			(5000 K)		
	0.3366	0.3369		0.3374	0.3554
R1	0.3369	0.3431	DO	0.3371	0.3493
KI	0.3407	0.3460	R9	0.3411	0.3522
	0.3403	0.3398		0.3415	0.3587
	0.3403	0.3398		0.3415	0.3587
DO.	0.3407	0.3460		0.3411	0.3522
R2	0.3446	0.3491	RA	0.3451	0.3554
	0.3440	0.3427		0.3457	0.3621
	0.3446	0.3491		0.3451	0.3554
	0.3440	0.3427		0.3457	0.3621
R3	0.3477	0.3458	RB	0.3500	0.3655
	0.3485	0.3522	•	0.3492	0.3587
	0.3485	0.3522	- RC	0.3492	0.3587
	0.3477	0.3458		0.3500	0.3655
R4	0.3514	0.3487		0.3542	0.3690
	0.3524	0.3554		0.3533	0.3620
	0.3371	0.3493		0.3376	0.3616
	0.3369	0.3431		0.3374	0.3554
R5	0.3407	0.3460	RD	0.3415	0.3587
	0.3411	0.3522	•	0.3420	0.3652
	0.3407	0.3460		0.3415	0.3587
	0.3411	0.3522		0.3420	0.3652
R6	0.3451	0.3554	RE	0.3463	0.3687
	0.3446	0.3491	•	0.3457	0.3621
	0.3446	0.3491		0.3457	0.3621
	0.3451	0.3554		0.3463	0.3687
R7	0.3492	0.3587	RF	0.3507	0.3724
	0.3485	0.3522		0.3500	0.3655
	0.3485	0.3522		0.3500	0.3655
	0.3492	0.3587		0.3507	0.3724
R8	0.3533	0.3620	RG	0.3551	0.3760
	0.3524	0.3554		0.3542	0.3690

Region	CIEx	CIE y	Region	CIEx	CIE y
		Q rank	(5700 K)		
	0.3218	0.3298		0.3211	0.3407
04	0.3222	0.3243		0.3215	0.3353
Q1	0.3258	0.3275	Q9	0.3254	0.3388
	0.3258 0.3275 0.3256 0.3331	0.3252	0.3444		
	0.3256	0.3331		0.3252	0.3444
00	0.3258	0.3275		0.3254	0.3388
Q2	0.3294	0.3306	QA	0.3293	0.3423
	0.3294 0.3364	0.3293	0.3481		
	0.3294	0.3364		0.3293	0.3481
	0.3294	0.3306		0.3293	0.3423
Q3	0.3330	0.3338	QB	0.3332	0.3458
	0.3331	0.3398		0.3333	0.3518
	0.3331	0.3398	QC	0.3333	0.3518
	0.3330	0.3338		0.3332	0.3458
Q4	0.3366	0.3369		0.3371	0.3493
	0.3369	0.3431	0.3374	0.3554	
	0.3215	0.3353		0.3207	0.3462
0.5	0.3218	0.3298		0.3211	0.3407
Q5	0.3256	0.3331	QD	0.3252	0.3444
	0.3254	0.3388		0.3250	0.3501
	0.3254	0.3388		0.3250	0.3501
00	0.3256	0.3331	0.5	0.3252	0.3444
Q6	0.3294	0.3364	QE	0.3293	0.3481
	0.3293	0.3423		0.3292	0.3539
	0.3293	0.3423		0.3292	0.3539
07	0.3294	0.3364	0.5	0.3293	0.3481
Q7	0.3331	0.3398	QF	0.3333	0.3518
	0.3332	0.3458		0.3334	0.3578
	0.3332	0.3458		0.3334	0.3578
00	0.3331	0.3398	00	0.3333	0.3518
Q8	0.3369	0.3431	QG	0.3374	0.3554
	0.3371	0.3493		0.3376	0.3616



Region	CIEx	CIE y	Region	CIE x	CIE y
		P rank	(6500 K)		
	0.3068	0.3113		0.3048	0.3207
D4	0.3106	0.3150	DO	0.3089	0.3249
P1	0.3098	0.3199	P9	0.3080	0.3298
	0.3058	0.3160	0 0.3	0.3038	0.3256
	0.3106	0.3150		0.3089	0.3249
50	0.3144	0.3186		0.313	0.3290
P2 0.3137	0.3238	PA	0.3123	0.3341	
	0.3098	0.3199		0.3080 0.3298 0.3130 0.3290	
	0.3144	0.3186		0.3130	0.3290
50	0.3183	0.3224		0.3172	0.3332
P3	0.3177	0.3278	PB	0.3166	0.3384
	0.3137	0.3238		0.3123	0.3341
	0.3183	0.3224	PC	0.3172	0.3332
	0.3221	0.3261		0.3214	0.3373
P4	0.3218	0.3317		0.3210	0.3427
	0.3177	0.3278		0.3166	0.3384
	0.3058	0.3160		0.3038	0.3256
	0.3098	0.3199		0.3080	0.3298
P5	0.3089	0.3249	PD	0.3072	0.3348
	0.3048	0.3207		0.3028	0.3304
	0.3098	0.3199		0.3080	0.3298
	0.3137	0.3238		0.3123	0.3341
P6	0.3130	0.3290	PE	0.3115	0.3391
	0.3089	0.3249		0.3072	0.3348
	0.3137	0.3238		0.3123	0.3341
	0.3177	0.3278		0.3166	0.3384
P7	0.3172	0.3332	PF	0.3160	0.3436
	0.313	0.3290		0.3115	0.3391
	0.3177	0.3278		0.3166	0.3384
	0.3218	0.3317		0.3210	0.3427
P8	0.3214	0.3373	PG	0.3206	0.3481
	0.3172	0.3332		0.3160	0.3436

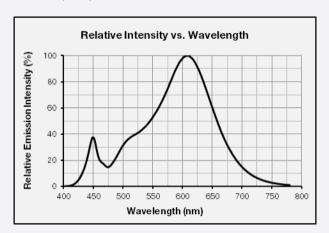
Note: Samsung maintains measurement tolerance of: Cx, $Cy = \pm 0.005$



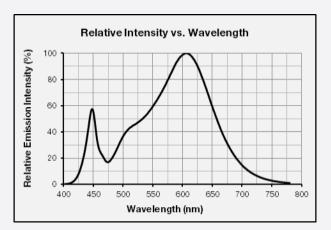
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 150$ mA, $T_s = 25$ °C)

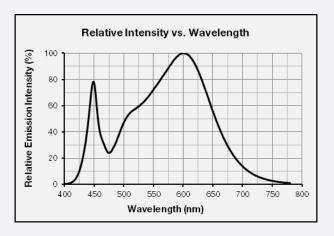
CCT: 2700 K (80 CRI)



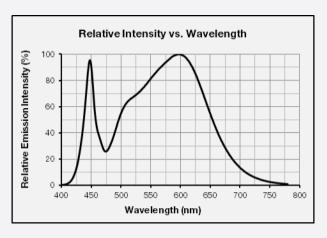
CCT: 3000 K (80 CRI)



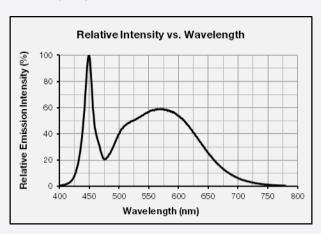
CCT: 3500 K (80 CRI)



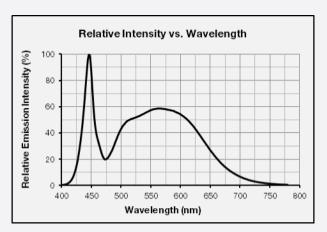
CCT: 4000 K (80 CRI)



CCT: 5000 K (80 CRI)

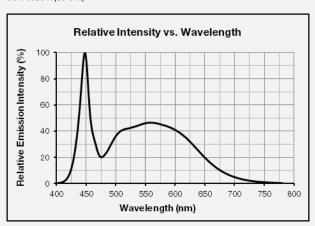


CCT: 5700 K (80 CRI)

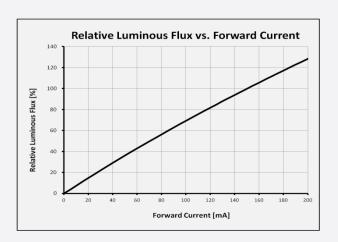


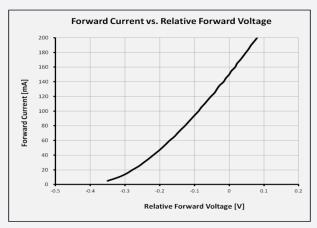


CCT: 6500 K (80 CRI)

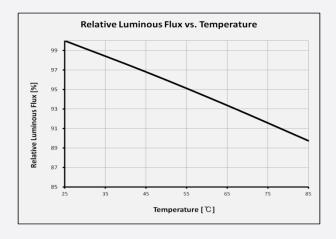


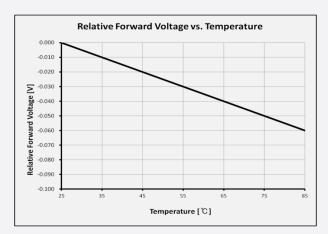
b) Forward Current Characteristics (T_s = 25 °C)





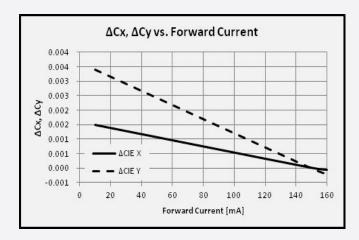
c) Temperature Characteristics (I_F = 150 mA)

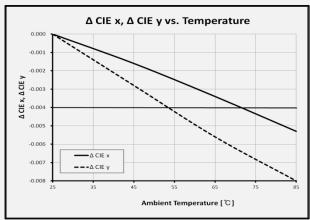




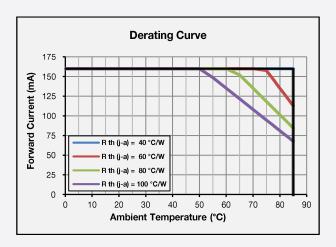


d) Color Shift Characteristics (I_F = 150 mA, T_s = 25 °C)

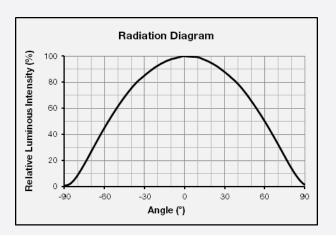




e) Derating Curve

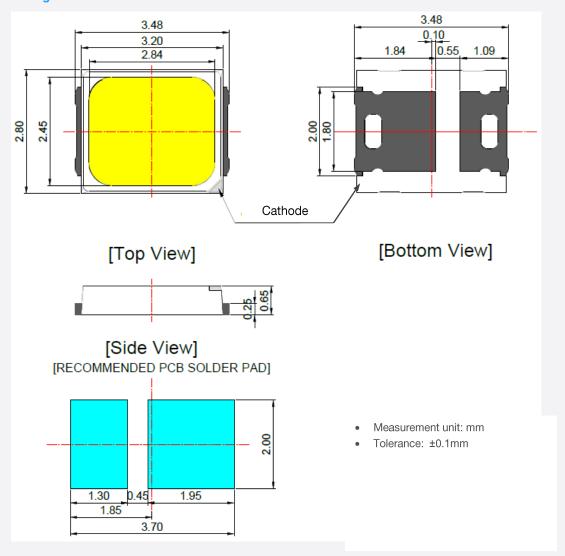


f) Beam Angle Characteristics ($I_F = 150$ mA, $T_s = 25$ °C)





4. Outline Drawing & Dimension



Notes:

- 1) T_s point and measurement method:
 - 1) Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T_s point.
 - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.



5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
Room Temperature Life Test	25 °C, DC 160 mA	1000 h	22
High Temperature Life Test	85 °C, DC 160 mA	1000 h	22
High Temperature Humidity Life Test	85 °C, 85 % RH, DC 160 mA	1000 h	22
Low Temperature Life Test	-40 °C, DC 160 mA	1000 h	22
Powered Temperature Cycle Test	-45 °C \sim 85 °C, each 20 min, on/off 5 min Temp. Change time 100min, DC 160 mA	100 cycles	22
Temperature Cycle	-45°C / 15 min ↔ 125 °C / 15 min	200 cycles	100
High Temperature Storage	85 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	R ₁ : 10 MΩ R ₂ : 1.5 kΩ C: 100 pF V: ±2 kV	5 times	30

b) Criteria for Judging the Damage

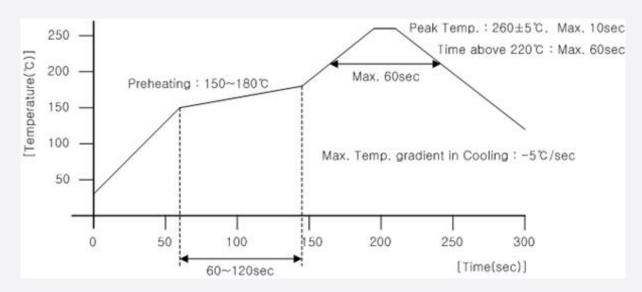
lh a sea	Complete I	Test Condition	Limit		
ltem	ltem Symbol	$(T_s = 25 ^{\circ}C)$	Min	Max	
Forward Voltage	V _F	$I_F = 150 \text{ mA}$	Init. Value * 0.9	Init. Value * 1.1	
Luminous Flux	Ф	I _F = 150 mA	Init. Value * 0.7	Init. Value * 1.1	



6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



b) Manual Soldering Conditions

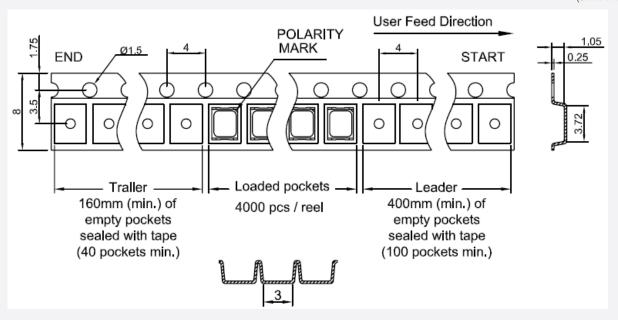
Not more than 5 seconds @ max. 300 °C, under soldering iron.



7. Tape & Reel

a) Taping Dimension

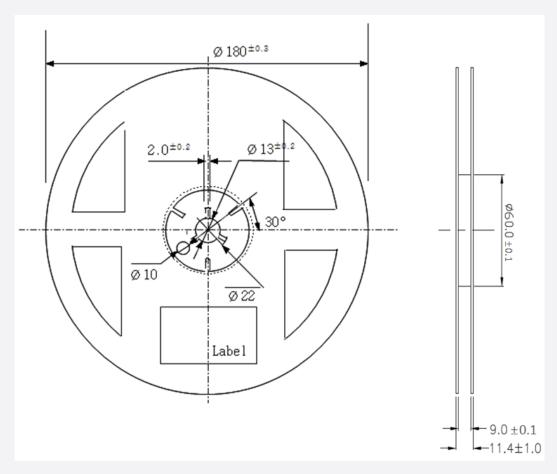
(unit: mm)





b) Reel Dimension (max 4,000 pcs)

(unit: mm)



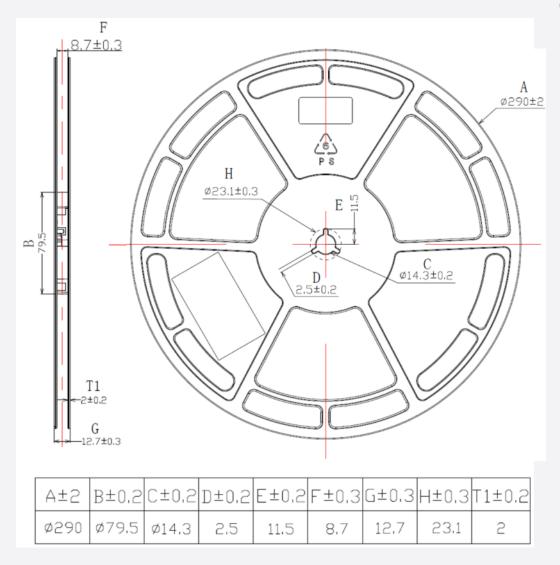
Notes:

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) All dimensions are millimeters (tolerance: ±0.2mm)
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag



c) Reel Dimension (max 12,000 pcs)

(unit: mm)



Notes:

1) Quantity: The quantity/reel is 12,000 pcs

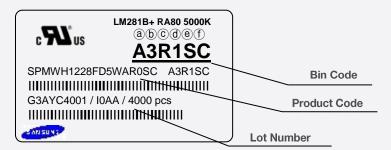
2) All dimensions are millimeters (tolerance: ±0.2mm)

3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag



8. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 6)

Bin Code:

(a) (b): Forward Voltage bin (refer to page 10)(c) (c) (d): Chromaticity bin (refer to page 11-18)(e) (f): Luminous Flux bin (refer to page 7)

b) Lot Number

The lot number is composed of the following characters:



123456789 / Iabc / 4,000 pcs

① : Production site (S: Giheung, Korea, G: Tianjin, China)

2 : 3 or P (LED)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

(Z: 2015, A: 2016, B: 2017...)

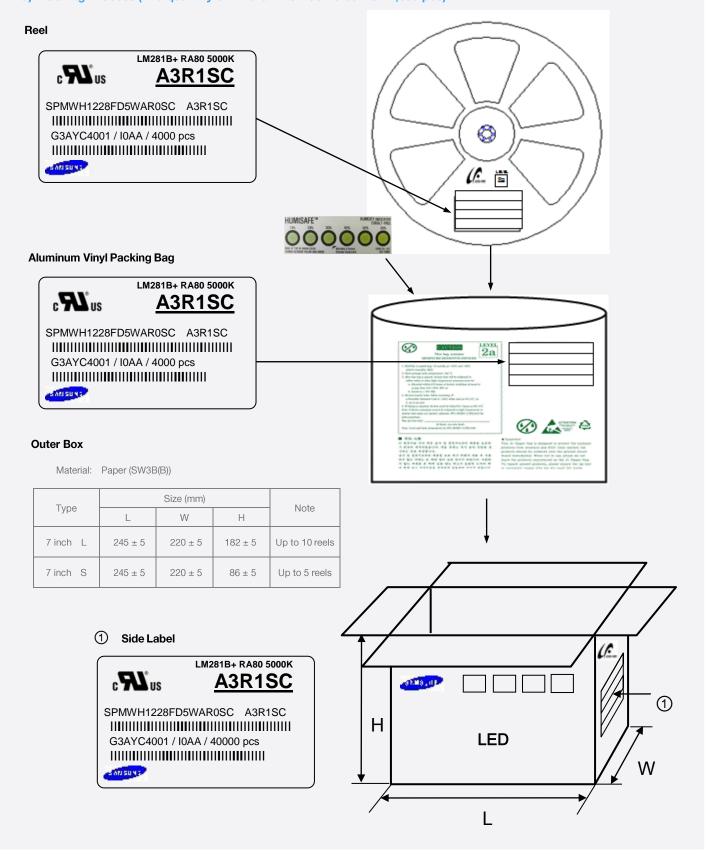
(5)
 (6)
 (1~9, A, B, C)
 (1~9, A, B~V)

(7)8(9) (a)b(c) : Product serial number



9. Packing Structure

a) Packing Process (The quantity of PKG on the Reel to be Max 4,000 pcs)





b) Packing Process (The quantity of PKG on the Reel to be Max 12,000 pcs) Reel LM281B+ RA80 5000K A3R1SC SPMWH1228FD5WKR0SC A3R1SC G3AYC4001 / I0AA / 12000 pcs General . **Aluminum Vinyl Packing Bag** 00000 LM281B+ RA80 5000K c**FL**°us A3R1SC SPMWH1228FD5WKR0SC A3R1SC 0 G3AYC4001 / I0AA / 12000 pcs SAMSUNG G. **Outer Box** LM281B+ RA80 5000K c**SL**°us A3R1SC SPMWH1228FD5WKR0SC A3R1SC 1 REEL/SHIELD BAG G3AYC4001 / I0AA / 360000 pcs 300 5 INNER/OUT BOX - 6 REEL/INNER BOX



c) Packing Process for kitting

Reel

Kitting 'A'

c**FL**°us

LM281B+ RA80 ★K

SPMWH1228FD5WA★KSC A3★1SC

G3AW94001 / I0AA / 4000 pcs

Kitting 'B'

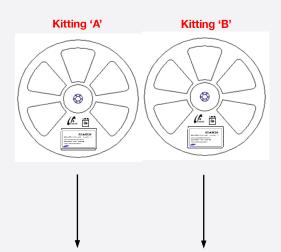
LM281B+ RA80 ★K



SPMWH1228FD5WA★KSC A3★CSC

...... G3AW94001 / I0AA / 4000 pcs





Aluminum Vinyl Packing Bag

Kitting 'A'



LM281B+ RA80 ★K

A3 ★1SC

SPMWH1228FD5WA★KSC A3★1SC

G3AW94001 / I0AA / 4000 pcs

SAMERAS

Kitting 'B'



LM281B+ RA80 ★K

A3★CSC

SPMWH1228FD5WA★KSC A3★CSC



G3AW94001 / I0AA / 4000 pcs

Outer Box

Kitting 'A'

c**FL**°us

LM281B+ RA80 ★K

A3★1SC

SPMWH1228FD5WA★KSC A3★1SC

...... G3AW94001 / I0AA / 20000 pcs

[BOX Label]

Kitting 'B'



LM281B+ RA80 ★K

A3★CSC

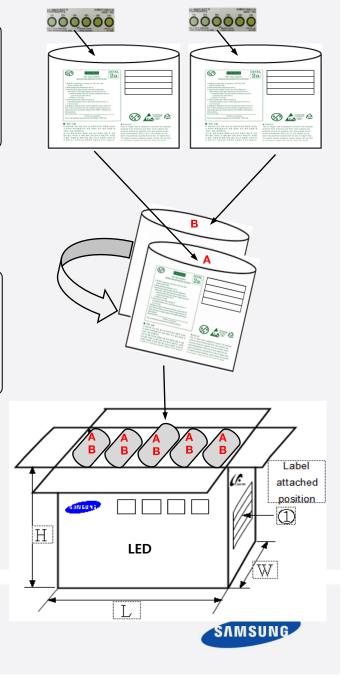
SPMWH1228FD5WA★KSC A3★CSC

..... G3AW94001 / I0AA / 20000 pcs

[BOX Label]

Material: Paper (SW3B(B))

Typo		Size (mm)		Note
Туре	L	W	Н	Note
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels



c) Aluminum Vinyl Packing Bag



CAUTION

2a

This bag contains MOISTURE SENSITIVE DEVICES

- Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- 2. Peak package body temperature: 240 °C
- After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
 - b. Stored at < 10% RH
- Devices require bake, before mounting, if:

 a. Humidity Indicator Card is > 60% when read at 23±5°C, or
 b. 2a is not met.
- 5. If baking is required, devices must be baked for 10 ~24 hours at 60±5°C Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag seal due date:

(If blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020



211° 127° 1

SAMERAS





LM281B+ RA80 5000K

SPMWH1228FD5WAR0SC A3R1SC

G3AYC4001 / I0AA / 4000 pcs

A3R1SC



■ 주의 사항

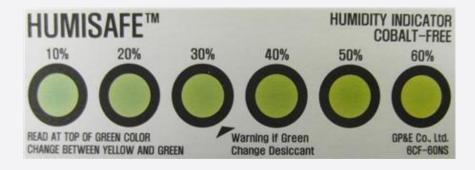
이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하 기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 설 시하는 것을 권장합니다.

습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용 하지 않는 자재는 본 팩에 넣어 보관 하시기 바랍니다. 사용하 지 않는 자재를 본 팩에 넣을 때는 반드시 동봉된 드라이 팩 과 함께 넣고 지퍼부분을 완전하게 밀봉하여 주시기 바랍니다.

■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

d) Humidity Indicator Card inside Aluminum Vinyl Bag





10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH*Note 1, or
 b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH*Note 2, or
 c. Stored at <10 % RH.

*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

	Package Type and	Moisture Sensitivity			ximum Percent	t Relative Humi	dity		Temperature
	Body Thickness	Level							romporataro
	Body Thickness <2.1mm		80	oo	28	1	1	1	30°C
		Level 2a		6	o	2	1	1	25°C
			0 0	o o	o o	2	2	1	20°C

- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at $23 \pm 5 \degree$ C.
- 8) Devices must be baked for $10\sim24$ hours at 60 ± 5 °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)
 - The LED from Samsung uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.



Legal and additional information.

About Samsung Electronics Co., Ltd.

Samsung Electronics Co., Ltd. is a global leader in technology, opening new possibilities for people everywhere. Through relentless innovation and discovery, we are transforming the worlds of TVs, smartphones, tablets, PCs, cameras, home appliances, printers, LTE systems, medical devices, semiconductors and LED solutions. To discover more, please visit www.samsungled.com.

Copyright © 2018 Samsung Electronics Co., Ltd. All rights reserved.

Samsung is a registered trademark of Samsung Electronics Co., Ltd.

Specifications and designs are subject to change without notice. Non-metric weights and measurements are approximate. All data were deemed correct at time of creation. Samsung is not liable for errors or omissions. All brand, product, service names and logos are trademarks and/or registered trademarks of their respective owners and are hereby recognized and acknowledged.

Samsung Electronics Co., Ltd. 95, Samsung 2-ro Giheung-gu Yongin-si, Gyeonggi-do, 446-711 KOREA

www.samsungled.com

